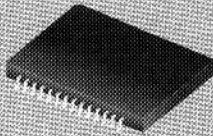
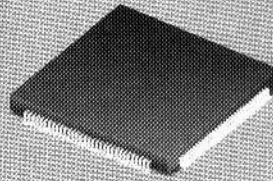




CPC2-028-F-03-SG



CPC4-128-S-SG



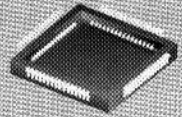
CPC2-020-S-01-SG



CPC2-016-S-02-SG-CU



CPC4-064-S-SG



# CHIP PACKAGE CPC2, CPC4 SERIES

## SPECIFICATIONS

### Materials:

**Insulator Material:**  
Liquid Crystal Polymer  
**Contact Material:**  
Phosphor Bronze  
**Operating Temp Range:**  
-65°C to +105°C with Tin;  
-65°C to +125°C with Gold  
**Plating:**  
Au over 50μ" (1,27μm) Ni  
**Current Rating:**  
Testing Now!  
**Max Processing Temp:**  
230°C for 60 seconds  
**SMT Lead Coplanarity:**  
(0,10mm) .004" max

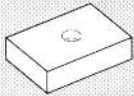
CPC2	NO. OF POSITIONS	LEAD PITCH	BODY STYLE	PLATING OPTION	OTHER OPTION
	004, 008, 010, 016, 020, 024, 028	-S = (0,64mm) .025" Pitch -F = (1,27mm) .050" Pitch	Specify BODY STYLE from chart	-SG = 30μ" (0,76μm) Soft Gold (.9999 pure)	Leave blank for Cavity Down -CU = Cavity Up -LDC = (1,52mm) .060" thick cupped lid with (0,76mm) .030" cavity -LDF = (0,76mm) .030" thick flat lid

LEAD PITCH	D
-S	(0,64) .025
-F	(1,27) .050

BODY STYLE	A	B	C
-01	(3,81) .150	(7,54) .297	(9,68) .381
-02	(7,62) .300	(11,35) .447	(13,49) .531
-03	(12,70) .500	(16,43) .647	(18,57) .731

## ALSO AVAILABLE

Optional lids for chip/wire bond protection.



CPC4	NO. OF POSITIONS	S	PLATING OPTION	OTHER OPTION
	-064, -128		-SG = 30μ" (0,76μm) Soft Gold (.9999 pure)	Leave blank for Cavity Down -CU = Cavity Up -LDC = (1,52mm) .060" thick cupped lid with (0,76mm) .030" cavity -LDF = (0,76mm) .030" thick flat lid

NO. OF POSITIONS	A	B	C
064	(12,01) .473	(15,75) .620	(17,88) .704
128	(21,67) .853	(25,40) 1.000	(27,53) 1.084

**Note:** Some sizes, styles and options are non-standard, non-returnable.

*Due to technical progress, all designs, specifications and components are subject to change without notice.*